



## Emerging Materials and Their Use in Electronic Applications

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### Message from the Guest Editor

With the rapidly growing demand for next-generation electronic devices, new materials and devices have been extensively suggested over the past several decades. This Special Issue aims to broadly cover the emerging materials and their applications in electronic devices, ranging from theoretical understanding and the characterization of emerging electronic materials to the design, fabrication process, and analysis of electronic devices based on those emerging electronic materials. The following topics are particularly of interest: Emerging semiconductor materials (low-dimensional semiconducting materials, organic semiconductors, carbon nanotubes, and metal-oxide semiconductors); Dielectric materials (including organic dielectrics, inorganic dielectrics, and their hybrid forms). The demonstration of electronic devices is important to verify the practical applicability of newly developed electronic materials. This Special Issue covers various kinds of electronic devices, particularly thin-film transistors and related devices such as memories, integrated circuits, and sensors as well as other types of devices composed of new dielectric and/or semiconductor materials.





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## Message from the Editor-in-Chief

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